



N-Channel Enhancement Mode Power MOSFET

Description

The PE8345G uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

General Features

- $V_{DS} = 30V$, $I_D = 45A$

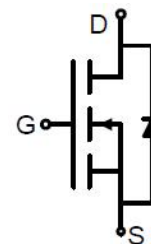
$$R_{DS(ON)} < 7.2m\Omega @ V_{GS}=10V$$

$$R_{DS(ON)} < 13m\Omega @ V_{GS}=4.5V$$

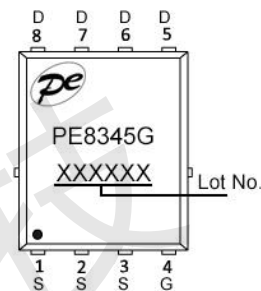
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

Application

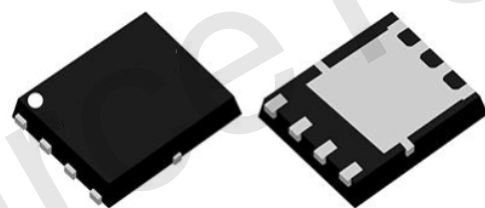
- Battery management
- Motor controller and driver
- PWM applications
- Load switch



Schematic diagram



Marking and pin assignment



DFN5x6-8L

Absolute Maximum Ratings (TC=25°C unless otherwise noted)

| Parameter | Symbol | Rating | Unit |
|--|------------------------|------------|------------|
| Drain-Source Voltage | V_{DS} | 30 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 45 | A |
| Drain Current-Continuous ($T_C=100^\circ C$) | $I_D(T_C=100^\circ C)$ | 33 | A |
| Pulsed Drain Current (Note 1) | I_{DM} | 180 | A |
| Maximum Power Dissipation | P_D | 31 | W |
| Avalanche Energy (L=0.1mH) | E_{AS} | 61 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 175 | $^\circ C$ |

Thermal Characteristic

| | | | |
|---|-----------------|---|--------------|
| Thermal Resistance, Junction-to-Case (Note 2) | $R_{\theta JC}$ | 4 | $^\circ C/W$ |
|---|-----------------|---|--------------|



Electrical Characteristics (TC=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|--------------|--|-----|------|-----------|------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 30 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=30V, V_{GS}=0V$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 1.2 | 1.5 | 2.2 | V |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS}=10V, I_D=14A$ | - | 6 | 7.2 | m Ω |
| | | $V_{GS}=4.5V, I_D=11A$ | - | 9.5 | 13 | m Ω |
| Forward Transconductance | g_{FS} | $V_{DS}=5V, I_D=10A$ | - | 32 | - | S |
| Dynamic Characteristics (Note 4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS}=15V, V_{GS}=0V, F=1.0MHz$ | - | 1300 | - | pF |
| Output Capacitance | C_{oss} | | - | 175 | - | pF |
| Reverse Transfer Capacitance (Note 4) | C_{rss} | | - | 121 | - | pF |
| Gate Resistance | R_g | $V_{DS}=0V, V_{GS}=0V, F=1.0MHz$ | - | 2.2 | - | Ω |
| Switching Characteristics | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=15V, I_D=2A, R_L=1\Omega, V_{GS}=10V, R_G=3\Omega$ | - | 7.2 | - | nS |
| Turn-on Rise Time | t_r | | - | 12 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 23 | - | nS |
| Turn-Off Fall Time | t_f | | - | 8 | - | nS |
| Total Gate Charge | Q_g | $V_{DS}=10V, I_D=25A, V_{GS}=10V$ | - | 28 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 3.5 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 7 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V_{SD} | $V_{GS}=0V, I_S=1A$ | - | - | 1.2 | V |
| Diode Forward Current (Note 2) | I_S | | - | - | 40 | A |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to product.



Typical Electrical and Thermal Characteristics



Figure 1 Switching Test Circuit



Figure 2 Switching Waveform

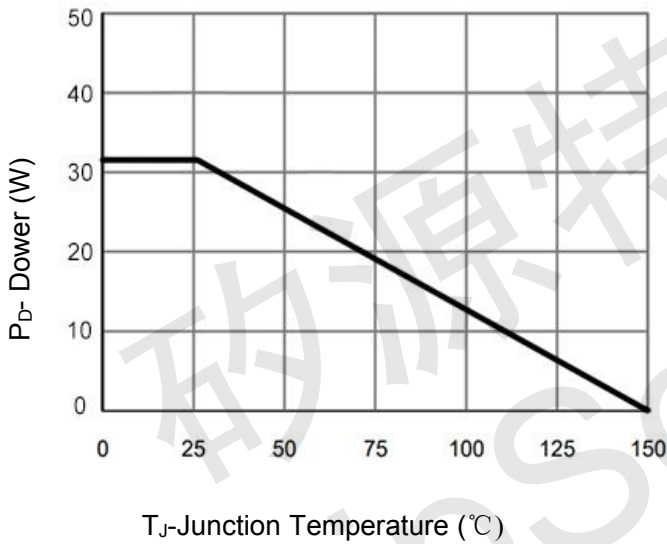


Figure 3 Power De-rating

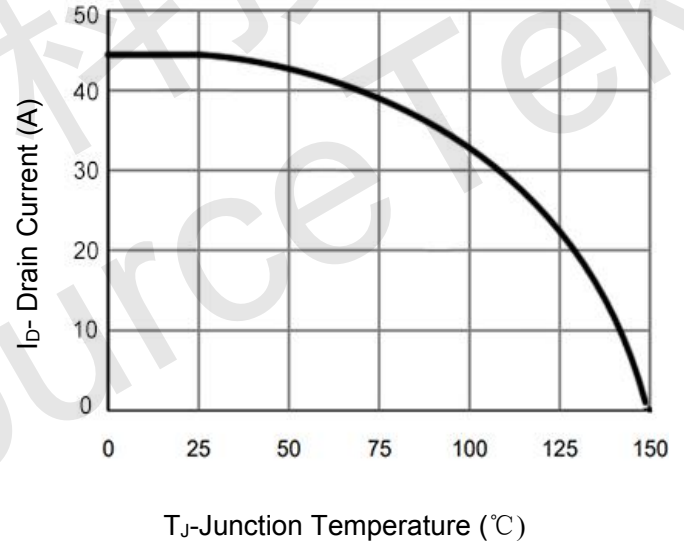


Figure 4 Drain Current

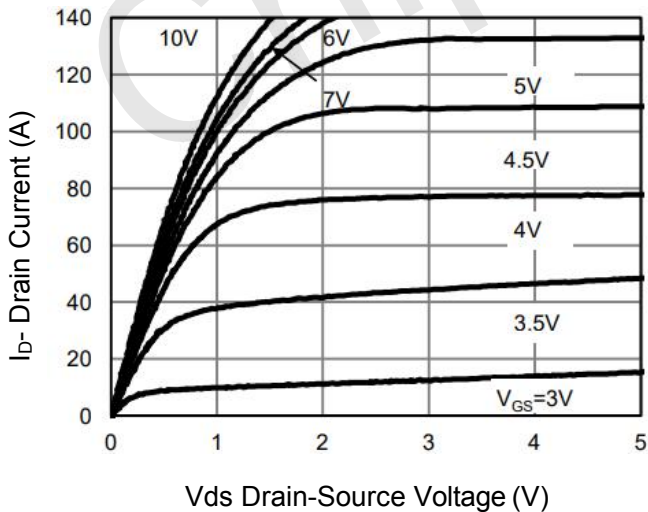


Figure 5 Output Characteristics

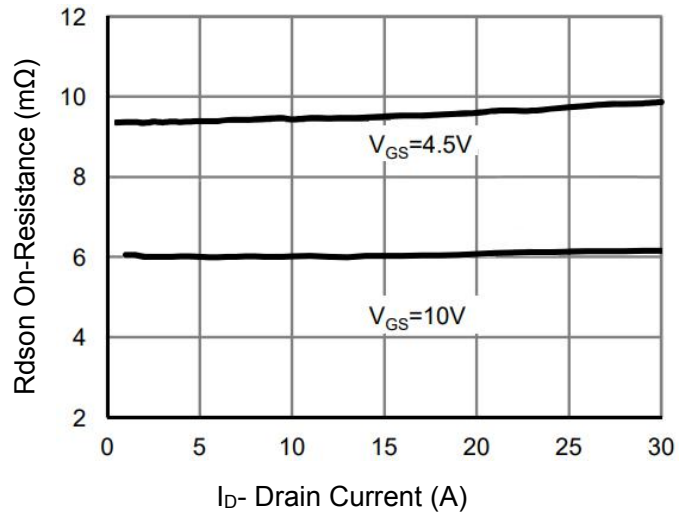
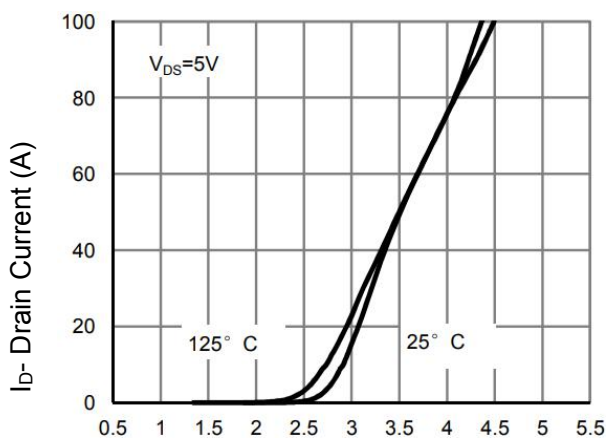
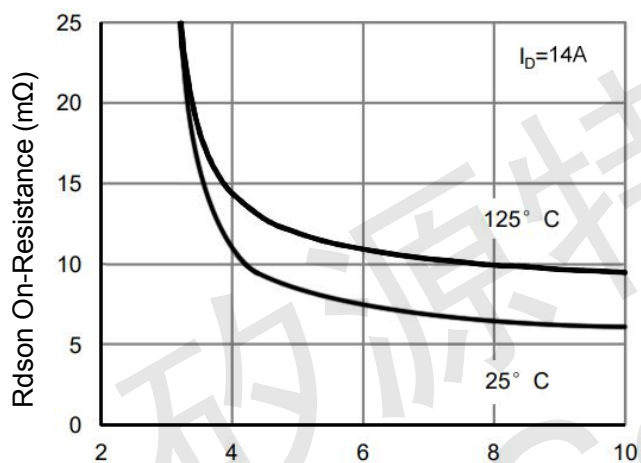


Figure 6 Rdson vs Drain Current



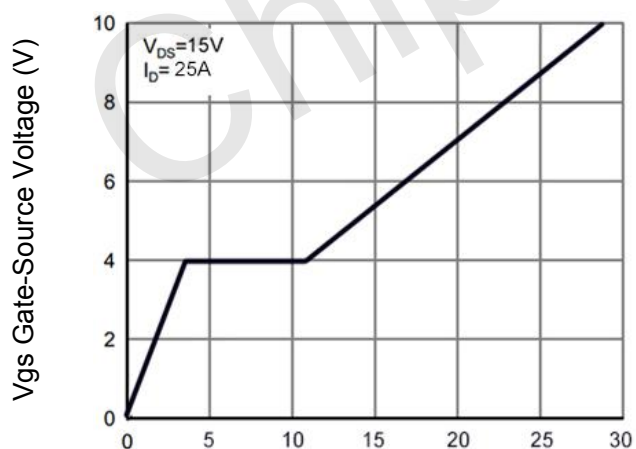
V_{GS} Gate-Source Voltage (V)

Figure 7 Transfer Characteristics



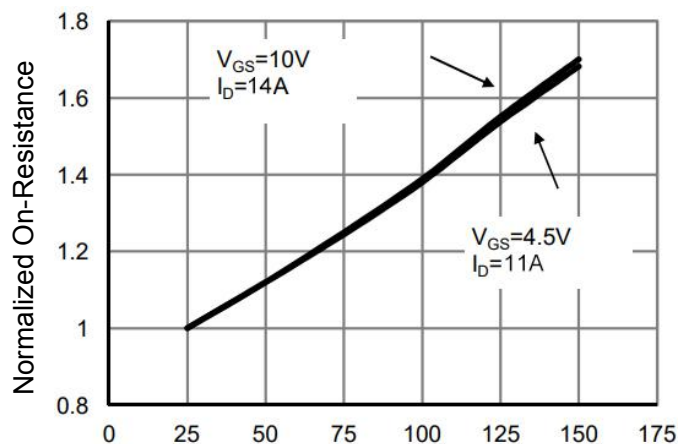
V_{GS} Gate-Source Voltage (V)

Figure 9 R_{dson} vs V_{GS}



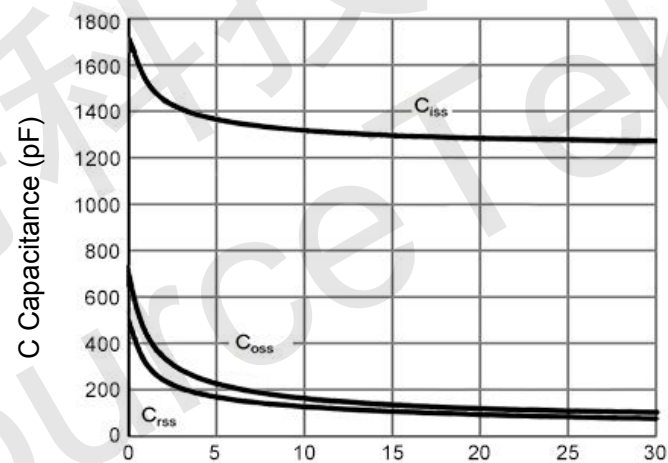
Q_G Gate Charge (nC)

Figure 11 Gate Charge



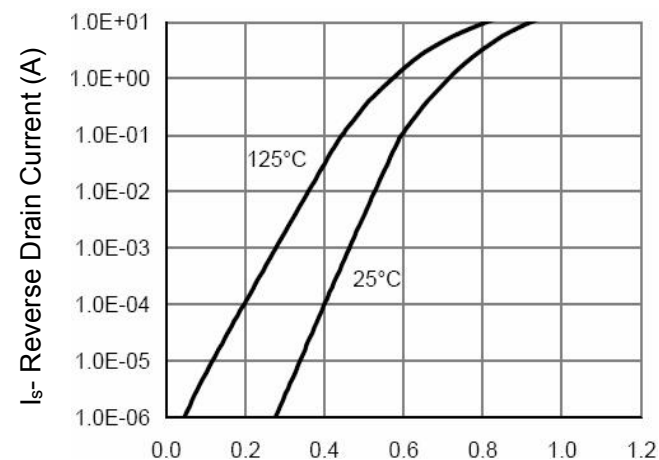
T_J Junction Temperature ($^\circ C$)

Figure 8 R_{dson} vs Junction Temperature



V_{DS} Drain-Source Voltage (V)

Figure 10 Capacitance vs V_{DS}



V_{SD} Source-Drain Voltage (V)

Figure 12 Source- Drain Diode Forward

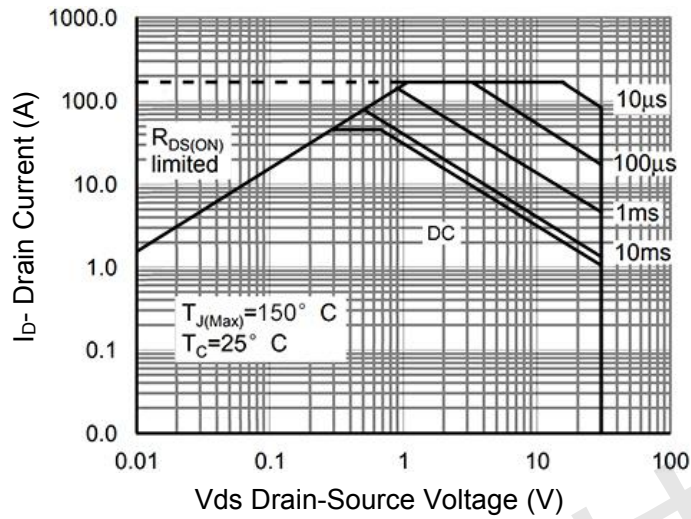


Figure 13 Safe Operation Area

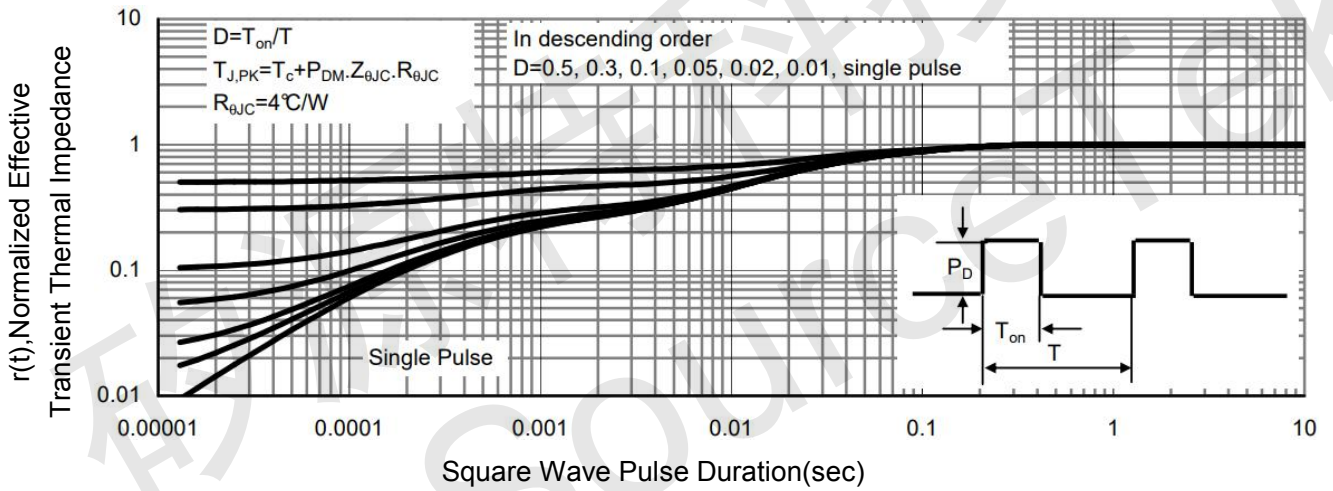
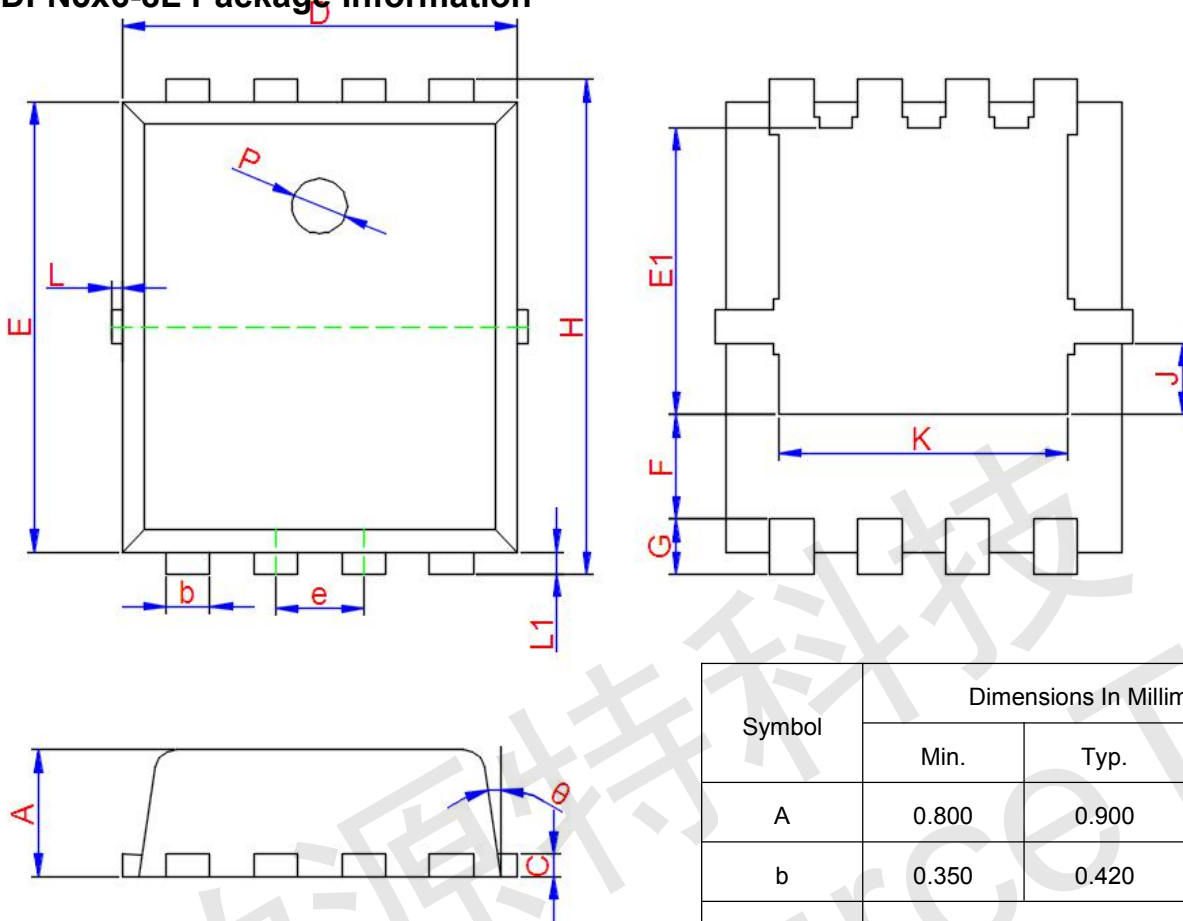


Figure 14 Normalized Maximum Transient Thermal Impedance



DFN5x6-8L Package Information



| Symbol | Dimensions In Millimeters | | |
|--------|---------------------------|-------|-------|
| | Min. | Typ. | Max. |
| A | 0.800 | 0.900 | 1.000 |
| b | 0.350 | 0.420 | 0.490 |
| c | 0.254TYP. | | |
| D | 4.900 | 5.000 | 5.100 |
| e | 1.270TYP. | | |
| E | 5.700 | 5.800 | 5.900 |
| E1 | 3.400TYP. | | |
| F | 1.400TYP. | | |
| G | 0.600TYP. | | |
| H | 5.950 | 6.080 | 6.200 |
| J | 0.950TYP. | | |
| K | 4.000TYP. | | |
| L | - | - | 0.150 |
| L1 | 0.100 | 0.140 | 0.180 |
| P | 1.000TYP. | | |
| θ | 6° | 10° | 14° |